

Standard part numbering

Standard devices

Die part numbers are derivative of the die process number, principal device part number, and packing method. For further information on die part numbering, visit Central's bare die webpage.

www.centrasemi.com/baredie

Example:

Small Signal NPN high voltage transistor die, 2N3439, in a chip tray (Waffle) Package.

CP310 - 2N3439 - CT

CENTRAL PROCESS NUMBER
(5 - 7 ALPHA/NUMERIC)

CPxxx = Transistor
 CPZxx = Zener Diode
 CPDxx = Diode
 CPQxx = TRIAC
 CPSxx = SCR

DEVICE TYPE NUMBER
(10 ALPHA/NUMERIC MAX)

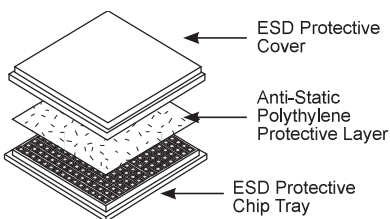
PACKING METHOD

See below for illustrations of each packing method.

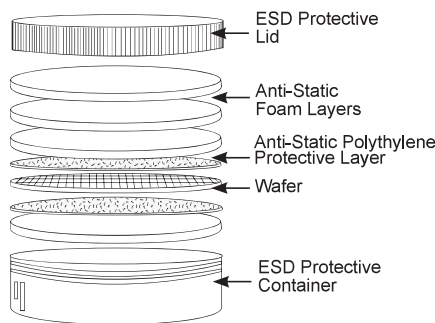
- CM** = Singulated bare die, 100% electrically tested, 100% visually inspected, reject die removed, tray (waffle) package
 - CT** = Singulated bare die, 100% electrically tested, reject die removed, tray (waffle) package
 - WN** = Wafer form, 100% electrically tested, reject die inked
 - WR** = Wafer form, 100% electrically tested, sawn and mounted on adhesive membrane and plastic ring, reject die inked
 - WS*** = Wafer form, 100% electrically tested, sawn and mounted on adhesive membrane and metal frame, reject die inked
- *WS is by special order only. Please contact your local Central sales representative.

Packing methods

Waffle pack (CM, CT)



Full unsawn wafers (WN)



Sawn wafer on plastic ring (WR) or metal frame* (WS)

